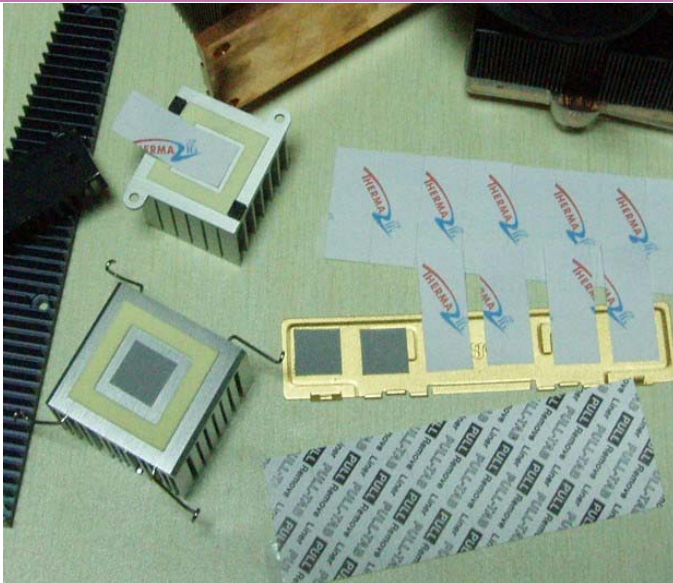


## Phase Change Thermal Interface Materials



### For Lowest Thermal Resistance :

- 0.018°C-in<sup>2</sup> /W thermal resistance
- Naturally tacky at room temperature, no adhesive required
- No heat sink preheating required

### Applications Include:

- High Frequency Microprocessors
- Notebook and Desktop PCs
- Computer Servers
- Memory Modules
- Cache Chips
- IGBTs

**TIC800A series** is high performance phase change material. At 50°C, TIC800A series begins to soften and flow, filling the microscopic irregularities of both the thermal solution and the integrated circuit package surface, thereby reducing thermal resistance. TIC800A series is a flexible solid at room temperature and freestanding without reinforcing components that reduce thermal performance.

**TIC800A Series** shows no thermal performance degradation after 1,000 hours @ 130°C, or after 500 cycles, from -25°C to 125°C. The material softens and does not fully change state resulting in minimal migration (pump out) at operating temperatures.

Product Name	TIC803A	TIC805A	Test Method
Color	Ashy	Ashy	Visual
Thickness	0.003" (0.076mm)	0.005" (0.127mm)	
Thickness Tolerance	±0.0006" (±0.016mm)	±0.0008" (±0.020mm)	
Density	2.5g/cc		Helium Pycnometer
Temperature range	-25°C~125°C		
Phase Change Softening Temperature	50°C~60°C		
"Burn In" Temperature	70°C for 5 minutes		
Thermal Conductivity	2.5 W/mK		ASTM D5470 (modified)
Thermal Impedance @ 50 psi(345 KPa)	0.018°C-in <sup>2</sup> /W 0.11°C-cm <sup>2</sup> /W	0.02°C-in <sup>2</sup> /W 0.13°C-cm <sup>2</sup> /W	ASTM D5470 (modified)

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein.